INTERLINK ELECTRONICS

NASDAQ: LINK

Enabling Smarter Devices Through Advanced Sensing

Advanced sensors and printed electronics solutions for industrial, medical, consumer, and automotive applications

May 2026

Headquartered in Fremont, California USA

FORWARD-LOOKING STATEMENTS

This presentation contains "forward-looking statements" within the meaning of the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements can be generally identified by phrases such as "thinks," "anticipates," "believes," "estimates," "expects," "intends," "plans," and similar words. Forward-looking statements include statements about our acquisition program, our projected annual revenue run rate, and the effects of our recent acquisitions, including contributions to our products, manufacturing operations and the markets we serve.

Forward-looking statements are not guarantees of future performance and are inherently subject to uncertainties and other factors which could cause actual results to differ materially from the forward-looking statement. These statements are based upon, among other things, assumptions made by, and information currently available to, management, including management's own knowledge and assessment of the company's industry, R&D initiatives, competition and capital requirements.

Other factors and uncertainties that could affect the company's forward-looking statements include: our success in predicting new markets and the acceptance of our new products; efficient management of our infrastructure; the pace of technological developments and industry standards evolution; protection of our proprietary intellectual property; competition by alternative sophisticated as well as generic products; continued availability of raw materials for our products at competitive prices; disruptions in our manufacturing facilities; risks of international sales and operations including fluctuations in exchange rates; compliance with regulatory requirements applicable to our manufacturing operations; and customer concentrations.

Additional factors that could cause actual results to differ materially from those anticipated by our forward-looking statements are under the captions "Risk Factors" and "Management's Discussion and Analysis of Financial Condition and Results of Operations" in our most recent Annual Report (Form 10-K) or Quarterly Report (Form 10-Q) filed with the Securities and Exchange Commission. Forward-looking statements are made as of the date of this presentation, and we expressly disclaim any obligation to publicly update or revise any forward-looking statements.

TECHNOLOGY PLATFORMS ENABLING THE

A leader in the sensor and printed electronics industries

History and Market Position

Interlink Electronics is a vertically integrated technology company delivering advanced sensors and printed electronic solutions. Founded in 1985, we have been trusted by major OEMs across industrial, medical, consumer, automotive, and emerging smart technologies.

Technical Capabilities

We provide vertically integrated solutions through our global operations, combining design, manufacturing, and engineering expertise to deliver high-performance sensor and printed electronic products.

Intellectual Property & Experience

With 49 issued patents and 14 pending, we bring decades of know-how and institutional knowledge to every engagement. Our track record reflects nearly 40 years of success in the sensors and printed electronics industries.

Global Footprint

Our team members are located across headquarters in Fremont, California; manufacturing in Irvine, Scotland; high-volume production in Shenzhen, China; and sales office in Yokohama, Japan.

TECHNOLOGY PLATFORMS ENABLING THE DATA AND AI REVOLUTION

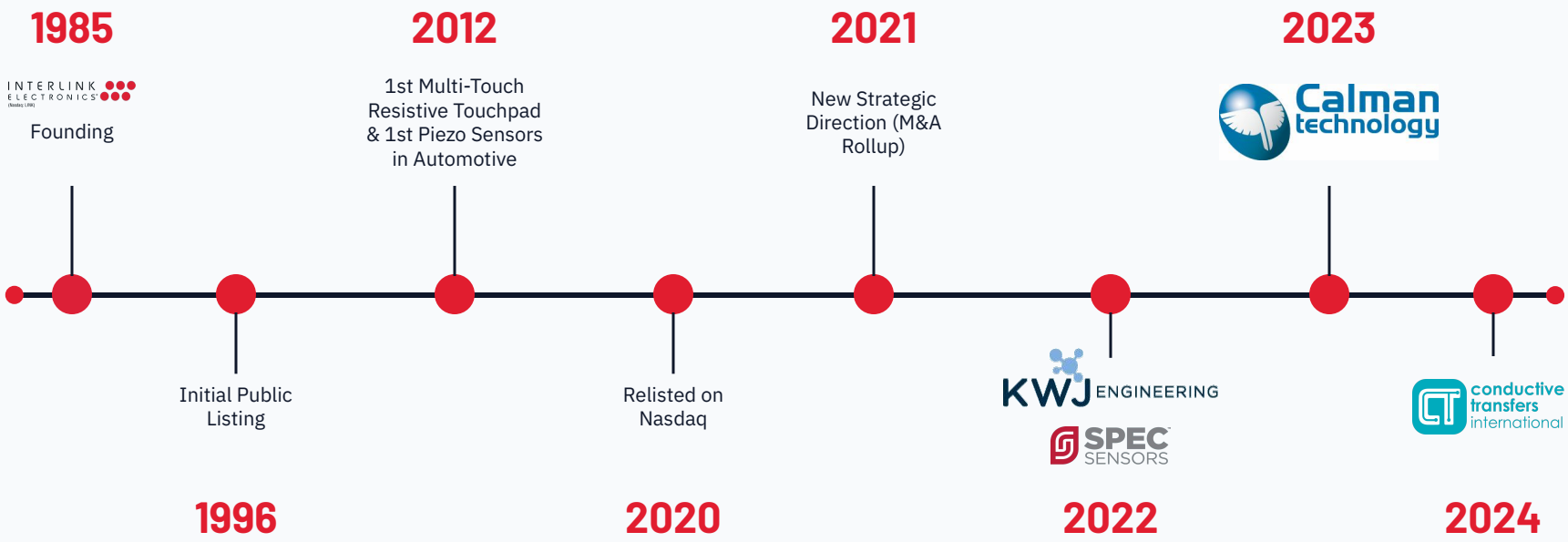
As a foundational enabler of next-gen technology, we provide critical sensors and interface solutions required to fuel smart devices, edge computing, environmental monitoring, and connected infrastructure.

INTERLINK ELECTRONICS

WHY INVEST IN INTERLINK ELECTRONICS

- Vertically integrated technology platform serving multiple high-growth verticals
- Positioned as a technology solutions provider for the global sensor, AI, and data-driven revolution
- Strong IP portfolio with 49 issued patents and 14 additional patents pending
- Proven track record with global OEMs and Tier-1 manufacturers
- Successful M&A execution of integration and value creation, with a growing pipeline of tuck-in and transformative opportunities

OVER 40 YEARS OF INNOVATION AND EXECUTION



STRATEGIC ACQUISITIONS INTEGRATION & VALUE CREATION

M&A Benefits

- Created a broader product and IP portfolio
- Expanded customer base and reference accounts
- Enhanced engineering talent
- Increased cross-selling potential across industries
- Established a proven blueprint and illustrative model for Interlink

Integration & Value creation

- Expanded product offerings and technology applications
- Created significant cross-selling opportunities
- Integrated a multi-decade IP portfolio in the gas sensing space
- Improved gross margins of businesses from mid-teens to over 30% within the first year post-acquisition

GLOBAL FOOTPRINT

USA - California

Corporate Headquarters, Silicon Valley R&D, Product Development, Gas Sensing Manufacturing

UK/Europe - Irvine

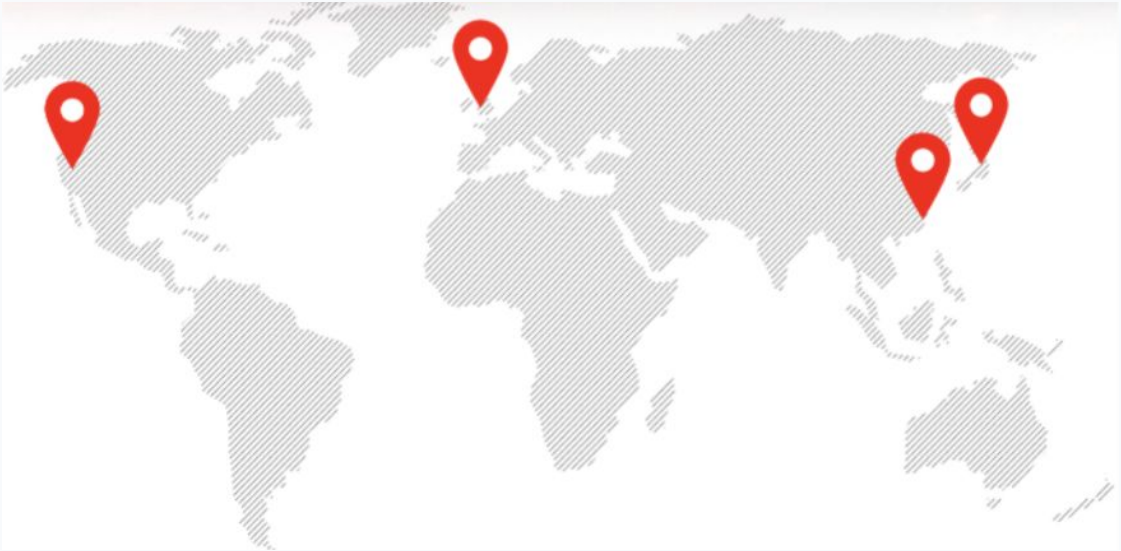
Membrane Keypads and Volume Printed Electronics Manufacturing

China - Shenzhen

Volume Manufacturing and Product Engineering

Japan - Yokohama

Sales Office and Customer Support

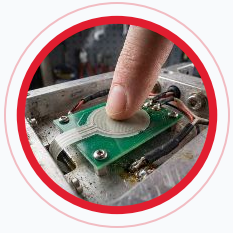


INTERLINK ELECTRONICS (Nasdaq: LINK)

FROM SENSOR TO SYSTEM ACROSS DIVERSE MARKETS

Cross-functional teams delivering end-to-end sensing solutions for mission-critical applications.

Printed Electronics



Force & Piezo Sensors

Wearable Technology

Gas Sensing Solutions

HMI & Membrane Keypad Solutions

CORE PRODUCT TECHNOLOGIES

Force Sensing

FSR technology for touch interfaces. Piezo film technology for dynamic strain and vibration detection.

Gas Sensing

Environmental air quality, industrial, health and food safety monitoring using innovative sensor technology.

Wearables

Smart textiles with functional sensing for health, rehabilitation, and fitness monitoring.

Printed Electronics

Cutting-edge printed sensing using proprietary technologies for medical diagnostics, human machine interface and rugged devices.

MARKET OPPORTUNITY

Interlink Electronics is well positioned in the printed and flexible sensors market.

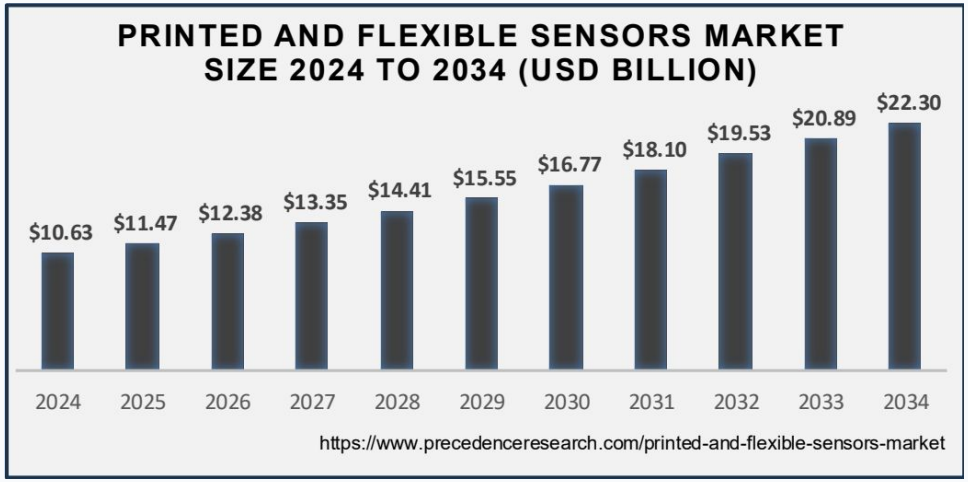
$11.47B
Current Market

$22.30B
2034 Forecast

7.69%
CAGR

Printed and Flexible Sensors Market

The global printed and flexible sensors market is currently valued at $11.47 billion and is forecasted to reach $22.30 billion by 2034 with a CAGR of 7.69% from 2024 to 2034. The growth in demand for printed and flexible sensors is driven from an increase in usages of consumer electronics and technology advancements in wearables and flexible electronics.



PAST & PRESENT CUSTOMERS

FINANCIAL SNAPSHOT

In Thousands	Q1 2026	2025 YE
Revenue	$3,074	$11,890
Gross Margin	43.5%	38.9%
Adjusted EBITDA	$(168)	($885)
Cash	$2,106	$2,724

Q1 2026 ending March 31, 2026

PATH TO $100M+ REVENUE IN 3-5 YEARS

Dual Growth Strategy

Organic Growth

- Continued product innovation
- Expansion into new geographies
- Investment in sales team
- Cross-selling opportunities across customer bases

Strategic Consolidation

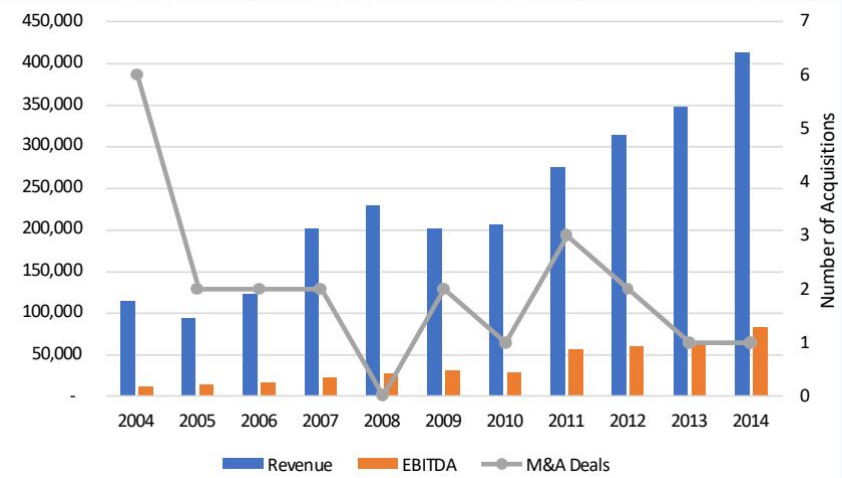
- Acquisitions in niche sensor categories
- Leverage Interlink's platform for integration

INTERLINK ELECTRONICS (Nasdaq: LINK)

OUR MODEL

Measurement Specialties - 10 Year Rollup

Revenue, EBITDA & M&A Deals



Stock Price ($3.77 to $86.00)

LEADERSHIP

Steven N. Bronson

Chairman, President & CEO

Steven N. Bronson became Chairman and CEO of Interlink Electronics in 2010 and assumed the role of President in 2011. Since then, he has focused on strategic priorities, mission-critical decisions, and acquisition-led platform expansion.

Ryan J. Hoffman

Chief Financial Officer

Ryan J. Hoffman brings more than two decades of accounting, audit, and financial leadership experience to Interlink.
As CFO, he oversees financial strategy, reporting, capital planning, and corporate development support for the company's operating platforms.

Declan Flannery

VP, Force Sensing

With nearly 30 years of experience across international operations, sensor design and manufacturing, product management, and project delivery, Declan has been central to Interlink's growth in printed electronics and force sensing.

Sreenivasa (Sreeni) RAO

VP, Gas & Environmental Sensing

Sreeni Rao leads Interlink's gas and environmental sensing solutions portfolio, helping align sensor elements, modules, instruments, and OEM programs across the broader gas platform.

INNOVATION, SCALE AND TRUST

Patent-Protected Innovation

Decades of expertise in developing custom, high-margin sensor solutions backed by strong patents creating high barriers to entry.

Vertically Integrated Manufacturing

End-to-end capabilities including design, prototyping, and manufacturing to deliver tailored solutions.

Global Scale & Infrastructure

Operations across United States, Europe, China, and Japan for efficient delivery and localized support.

Blue-Chip Reference Customers

Proven track record serving large-volume, global Tier 1 OEMs reflecting reliability and world-class capability.

Technical Knowledge and Engineering Depth

Deep expertise and growing portfolio of products available through global distribution platforms like DigiKey.

KEY TAKEAWAYS

INTERLINK ELECTRONICS – Smart. Printed. Sensors.

- Building the next-gen smart sensing global and scalable platform
- Positioned as the "pick and shovels" for the data and AI revolution
- Proven execution with margin-accretive acquisitions
- Scalable platform supported by global operations and IP
- Strong leadership team and path to $100M+ revenue

CONTACT

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INTERLINK ELECTRONICS

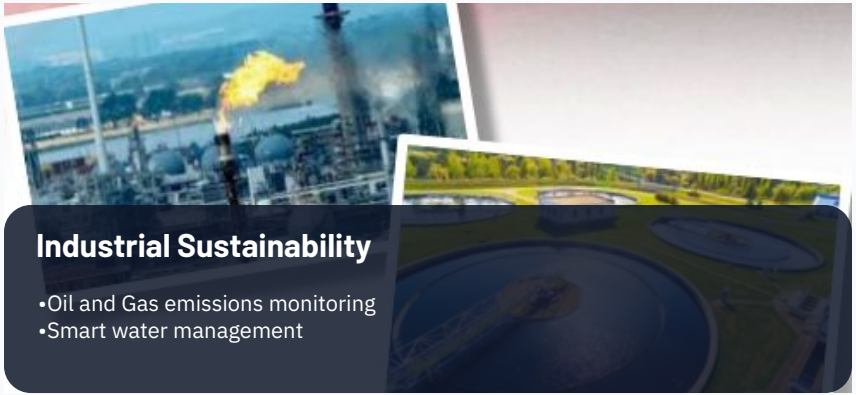
TRENDS & APPLICATIONS

Interlink Electronics

BUILDING LEADERSHIP TO ADDRESS MEGA TRENDS

Air Quality

- Indoor/outdoor air quality and safety
- Smart buildings via energy management
- Early wildfire monitoring



Industrial Sustainability

- Oil and Gas emissions monitoring
- Smart water management

Green Automotive

- EV Battery management
- H2 vehicle supply chain

Consumer Care and Wellness

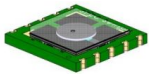
- Food safety and quality
- Substance abuse monitoring
- At-home health monitoring

SENSOR ELEMENTS FOR A BROAD RANGE OF GASES

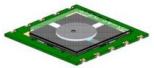
At Standard Conditions: 25 °C, 50% RH and 1 atm		
Gas Type	**Range, ppm**	**Resolution*, ppb**
CO – Carbon Monoxide	0 - 400	0.2
CO - Carbon Monoxide	0 - 20	0.03
EtOH – Ethanol	0 – 600	0.3
H2S – Hydrogen Sulfide	0 – 10	0.01
O3 - Ozone	0 – 20	0.02
Cl2 - Chlorine	0 – 20	0.02
NO2 – Nitrogen Dioxide	0 – 30	0.03
SO2 – Sulfer Dioxide	0 – 40	0.03
C2H4 - Ethylene	0 – 40	0.02
NO – Nitric Oxide	0 – 20	0.02
IAQ – Indoor Air Quality	0 – 100 (CO)	0.05
HCHO – Formaldehyde	0 – 20	0.03
RESP - Respiratory Irritants	0 – 20 (NO2)	0.02
H2 - Hydrogen	0 – 100	0.2

Indoor Air Quality (IAQ)	**Total Oxidants** VOC's, EtOH, CO, H2S, SO2
Respiratory Irritants	**Total Reductants** NO2, O3, Cl2
Breath Alcohol	**0.00 to 0.40 BAC** 0.01 BAC Resolution

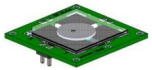
Available Sensor Packages



Thick Castellation



Thin Castellation



Pinned

INTERLINK ELECTRONICS (Nasdaq: LINK)

GAS SENSING APPLICATIONS & CUSTOMERS

Indoor Air Quality Monitor

Vape Detector for Buildings

Methane Emissions Monitor

Wearable Alcohol Monitor

Smart Mobile Disinfector

Building HVAC Control

OAQ / Wildfire Detector

Breath Health Monitor

Gas Leakage Sensor

Water Treatment Monitor

RUGGED TRACKPADS

- The world's top rugged laptop manufacturer uses VersaPad resistive touchpad technology
- Passes the Panasonic "Tough" specification
- So tough it withstands over 5 million stylus strokes
- USB, PS/2, I2C options available
- Can be used with finger, stylus, or glove — even in harsh environments
- Unique design aesthetic
- No additional driver required

INTERLINK ELECTRONICS (Nasdaq: LINK)

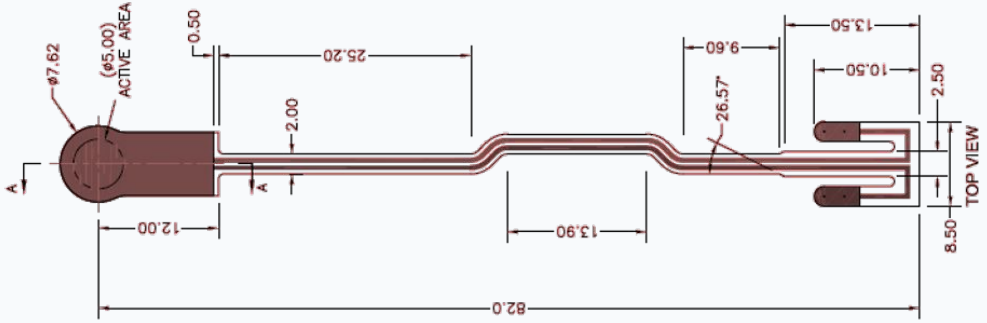
COLLISION DETECTION

- Over 30 years supplying this solution
- TrueBeam radiation oncology treatment delivery system uses pressure-sensitive bumper assemblies to detect collisions
- FSR can distinguish between a touch and a firm press in safety stop collision avoidance system
- Value added assembly including mechanical assembly and 100% electrical testing
- Traceability on every part
- Manufactured in ISO13485 facility

INTERLINK ELECTRONICS (Nasdaq: LINK)

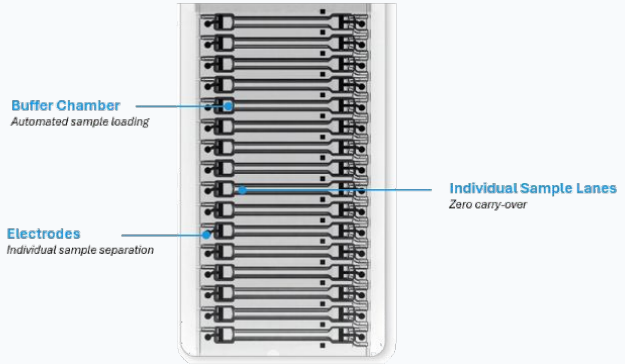
MEDICAL PROSTHETICS

- Custom FSR sensors for fingertips of world's most advanced prosthetic hand
- Adds sense of touch on all 5 fingers
- Custom FSR on FPC to provide required flexibility and durability



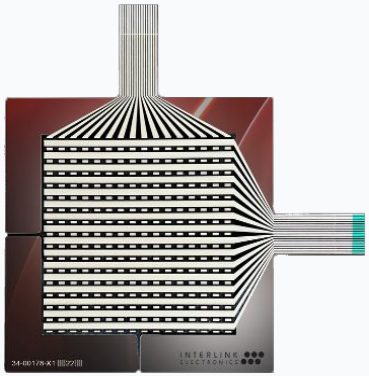
MEDICAL DIAGNOSTIC ELECTRODES

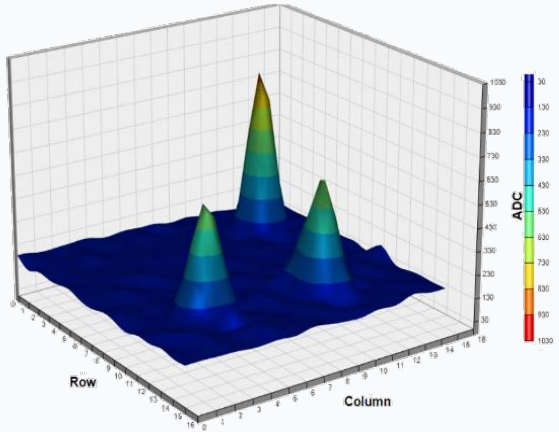
- Over 10 years in high volume manufacturing of electrodes for DNA & RNA quality control systems
- Leader in printing highly complex electrodes for the next generation of lateral flow medical diagnostics
- Medical manufacturing certification ISO 13485

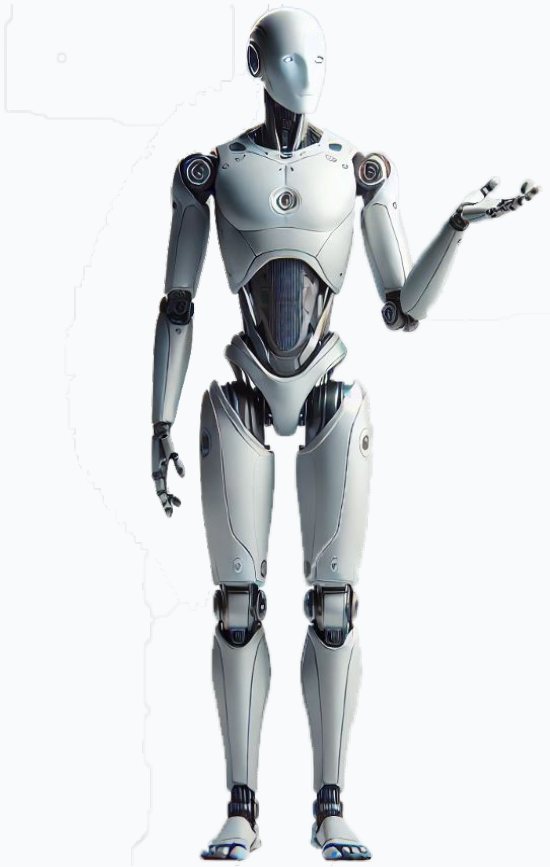


ROBOTIC

- Custom FSR Matrix Sensor for Feet
- Adds sense to the feet of the Robot for stabilization
- 1 pair for left and right feet
- Custom FSR on FPC to provide required flexibility and durability







SMART TEXTILE TECHNOLOGIES

Printed electrodes

ElastaTrode™

Printed electrodes, conducting electrical energy across the fabric surfaces.

Heater

ElastaTherm™

Printed heaters, conducting heat and fabric via our printing technology.

Pressure Sensing

ElastaSens™

Capacitive sensors, printed technology to detect stretch and pressure.

Hybrid Electronics

ElastaTronic™

Printed circuits, positioning and integrating electrical components onto fabric.

Seam Crossing

ElastaLink™

Seam crossing, connecting across stitched seams through bridging technology.

INNOVO SMART GARMENT

Since 2018, Conductive Transfers has supplied over 145,000 printed circuits to US MedTech Caldera Medical; for the FDA and CE approved Innovo © smart garment, which is used to treat urinary incontinence. Innovo© uses Conductive Transfers' ElastaTrode© technology, ensuring that the circuits are thin, light, stretchable, washable and cost effective.

The Innovo© product won the Irish Times "Innovation of the Year" award in 2019, the Conductive Transfer process has won the prestigious UK Kings innovation award in 2023 and a UK national Med Tech award in 2024

MYGO SMART GARMENT

The MyGo© is a soft garment exoskeleton with built in conductive transfer electrodes. It creates and boosts electrical signals to different nerves and muscles sequentially, throughout the body, helping patients stand, walk, and move functionally, where previously they were unable or with difficulty.

MyGo© have had multiple successful trials with our prototypes, helping paraplegic patients on their journey to walk again.

Prototype electrodes. Courtesy of MyGo4ward.

Paraplegic patient testing. Courtesy of MyGo4ward.

MYGO

CTD ElastaTrode